### SUBMINIATURE SOLID STATE LAMP

Part Number: AM27EC09

High Efficiency Red

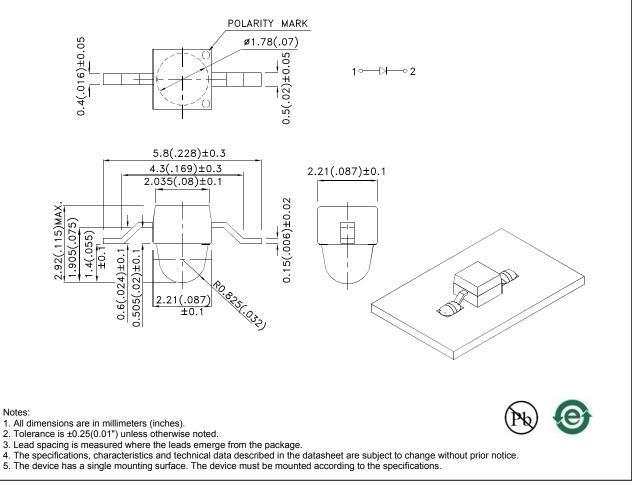
#### Features

- Subminiature package.
- Z-Bend lead.
- Long life solid state reliability.
- Low package profile.
- Package :1000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

#### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

#### **Package Dimensions**



SPEC NO: DSAD1325 APPROVED: WYNEC REV NO: V.8 CHECKED: Allen Liu DATE: APR/14/2011 DRAWN: J.Yu PAGE: 1 OF 5 ERP: 1202000247

#### Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
AM27EC09	High Efficiency Red (GaAsP/GaP)	Water Clear	50	100	20°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	High Efficiency Red	627		nm	I⊧=20mA	
λD [1]	Dominant Wavelength	High Efficiency Red	625		nm	I⊧=20mA	
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	I⊧=20mA	
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	I⊧=20mA	
lr	Reverse Current	High Efficiency Red		10	uA	Vr=5V	

Notes:

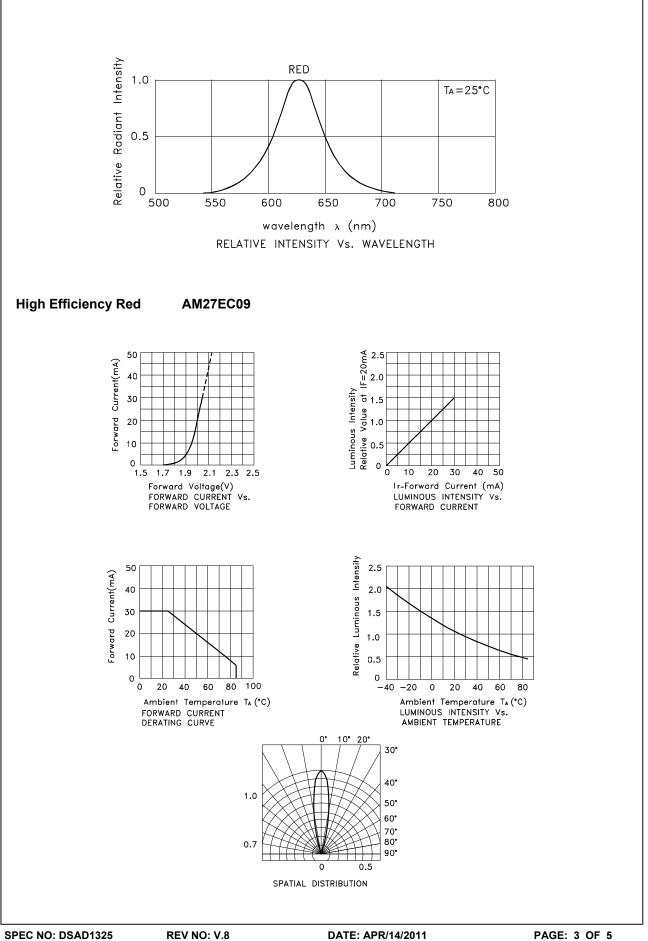
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

### Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	160	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note:

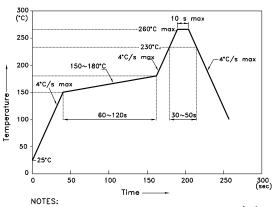
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



### **AM27EC09**

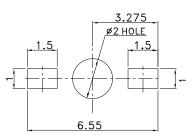
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

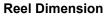
Reflow Soldering Profile For Lead-free SMT Process.

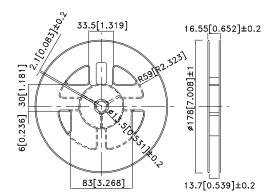


NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

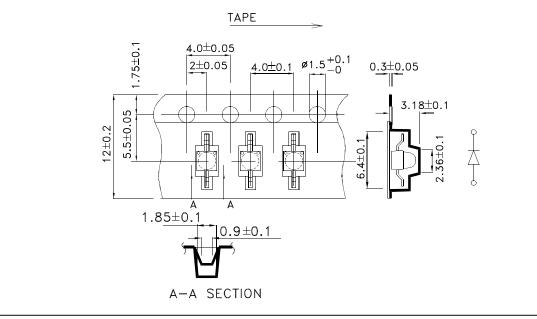
**Recommended Soldering Pattern** (Units : mm; Tolerance: ± 0.1)







**Tape Dimensions** (Units : mm)



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